

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

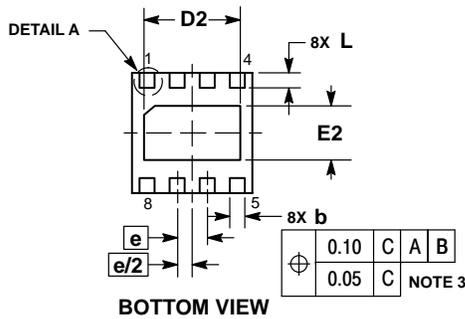
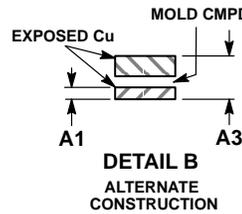
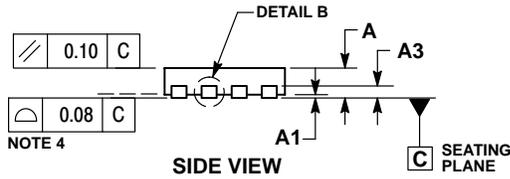
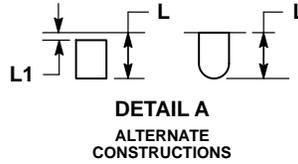
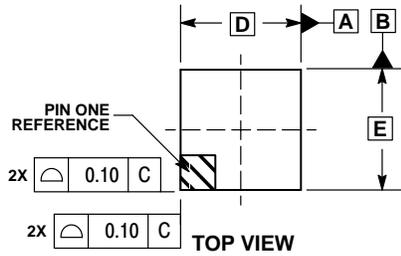
ON Semiconductor®



SCALE 2:1

UDFN8, 2x2
CASE 517AW
ISSUE A

DATE 13 NOV 2015

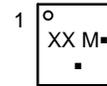


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. FOR DEVICE OPN CONTAINING W OPTION, DETAIL B ALTERNATE CONSTRUCTION IS NOT APPLICABLE.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.13 REF | |
| b | 0.18 | 0.30 |
| D | 2.00 BSC | |
| D2 | 1.50 | 1.70 |
| E | 2.00 BSC | |
| E2 | 0.80 | 1.00 |
| e | 0.50 BSC | |
| L | 0.20 | 0.45 |
| L1 | --- | 0.15 |

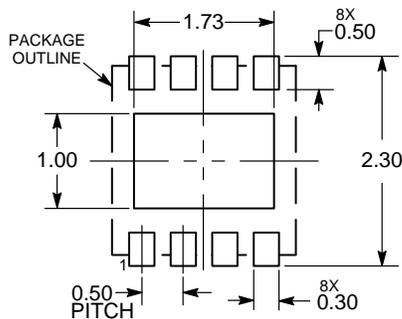
GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| REFERENCE: | | |
| DESCRIPTION: | UDFN8, 2X2 | PAGE 1 OF 2 |

